

ABSTRACT

A socket is provided which has an insulative housing surrounding a metal substrate. The substrate has an array of apertures which are located in spatially arranged order to accommodate the precise pattern desired for the device to be connected. Contact assemblies include stamped and formed contacts having an insulative plastic molded over a central section of the contact. The molded inserts are receivable in the apertures of the substrate and are later swaged to retain them and the contacts to the substrate. The substrates are located relative to a mating device by way of pins attached to the substrate. The pins are locked to the substrate by way of a locking device, whereby the pins are rotated and locked in place.